SN54ALS373A, SN54AS373, SN74ALS373A, SN74AS373
OCTAL TRANSPARENT D-TYPE LATCHES
WITH 3-STATE OUTPUTS

SDAS083C – APRIL 1982 – REVISED MARCH 2002

- **Eight Latches in a Single Package**
- **3-State Bus-Driving True Outputs**
- **Full Parallel Access for Loading**
- **Buffered Control Inputs**
- **pnp Inputs Reduce dc Loading on Data Lines**
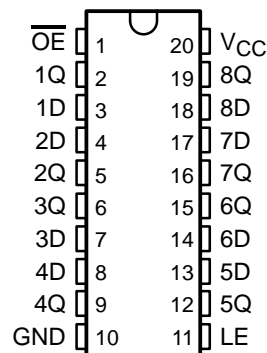
description

These octal transparent D-type latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.
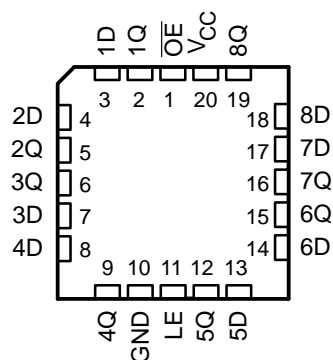
A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$ does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

SN54ALS373A, . . . J OR W PACKAGE
SN54AS373 . . . J PACKAGE
SN74ALS373A, SN74AS373 . . . DW, N, OR NS PACKAGE
(TOP VIEW)

$\overline{OE}$	1	20	V_{CC}
1Q	2	19	8Q
1D	3	18	8D
2D	4	17	7D
2Q	5	16	7Q
3Q	6	15	6Q
3D	7	14	6D
4D	8	13	5D
4Q	9	12	5Q
GND	10	11	LE

SN54ALS373A, SN54AS373 . . . FK PACKAGE
(TOP VIEW)

Top pins (left to right): 1D (3), 1Q (2), $\overline{OE}$ (1), V_{CC} (20), 8Q (19)

Left pins: 2D (4), 2Q (5), 3Q (6), 3D (7), 4D (8)

Right pins: 8D (18), 7D (17), 7Q (16), 6Q (15), 6D (14)

Bottom pins (left to right): 4Q (9), GND (10), LE (11), 5Q (12), 5D (13)

TEXAS INSTRUMENTS

SN54ALS373A, SN54AS373, SN74ALS373A, SN74AS373
OCTAL TRANSPARENT D-TYPE LATCHES
WITH 3-STATE OUTPUTS

ORDERING INFORMATION

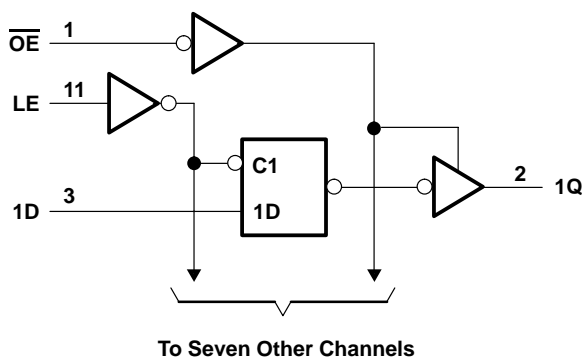| T$_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74ALS373AN	SN74ALS373AN
			SN74AS373N	SN74AS373N
	SOIC – DW	Tube	SN74ALS373ADW	ALS373A
		Tape and reel	SN74ALS373ADWR	
		Tube	SN74AS373DW	AS373
		Tape and reel	SN74AS373DWR	
	SOP – NS	Tape and reel	SN74ALS373ANSR	ALS373A
			SN74AS373NSR	74AS373
−55°C to 125°C	CDIP – J	Tube	SNJ54ALS373AJ	SNJ54ALS373AJ
			SNJ54AS373J	SNJ54AS373J
	CFP – W	Tube	SNJ54ALS373AW	SNJ54ALS373AW
	LCCC – FK	Tube	SNJ54ALS373AFK	SNJ54ALS373AFK
			SNJ54AS373FK	SNJ54AS373FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines
  are available at www.ti.com/sc/package.

FUNCTION TABLE
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

logic diagram (positive logic)

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (SN54ALS373A, SN74ALS373A) (unless otherwise noted)†

Supply voltage, V_{CC} .... 7 V
Input voltage, V_I .... 7 V
Voltage applied to any output in the high state or power-off state .... 5.5 V
Package thermal impedance, θ_{JA} (see Note 1): DW package .... 58°C/W
N package .... 69°C/W
NS package .... 60°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1:   The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		SN54ALS373A			SN74ALS373A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			−1			−2.6	mA
I_{OL}	Low-level output current			12			24	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54ALS373A		SN74ALS373A		UNIT
		MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency					MHz
t_w	Pulse duration, LE high	12		10		ns
t_{su}	Setup time, data before LE↓	10		10		ns
t_h	Hold time, data after LE↓	7		7		ns

TEXAS
INSTRUMENTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALS373A			SN74ALS373A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.5			−1.5	V
V_{OH}	V_{CC} = 4.5 V to 5.5 V,	I_{OH} = −0.4 mA	V_{CC}−2			V_{CC}−2			V
	V_{CC} = 4.5 V	I_{OH} = −1 mA	2.4	3.3					
		I_{OH} = −2.6 mA				2.4	3.2		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
		I_{OL} = 24 mA					0.35	0.5	
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			20			20	μA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.4 V			−20			−20	μA
I_I	V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	μA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.4 V			−0.1			−0.1	mA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.25 V	−20		−112	−30		−112	mA
I_{CC}	V_{CC} = 5.5 V	Outputs high		9	16		9	16	mA
		Outputs low		16	25		16	25	
		Outputs disabled		17	27		17	27	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX§				UNIT
			SN54ALS373A		SN74ALS373A		
			MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	2	17	2	12	ns
t_{PHL}			1	19	4	16	
t_{PLH}	LE	Any Q	6	29	6	22	ns
t_{PHL}			1	27	7	23	
t_{PZH}	$\overline{OE}$	Any Q	6	22	1	18	ns
t_{PZL}			5	24	5	20	
t_{PHZ}	$\overline{OE}$	Any Q	2	16	1	10	ns
t_{PLZ}			2	24	2	12	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

absolute maximum ratings over operating free-air temperature range (SN54AS373, SN74AS373) (unless otherwise noted)†

Supply voltage, V_{CC} .... 7 V
Input voltage, V_I .... 7 V
Voltage applied to any output in the high state or power-off state .... 5.5 V
Package thermal impedance, θ_{JA} (see Note 1): DW package .... 58°C/W
N package .... 69°C/W
NS package .... 60°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 2: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		SN54AS373			SN74AS373			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			−12			−15	mA
I_{OL}	Low-level output current			32			48	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54AS373		SN74AS373		UNIT
		MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency					MHz
t_w	Pulse duration, LE high	5.5*		4.5*		ns
t_{su}	Setup time, data before LE↓	2*		2*		ns
t_h	Hold time, data after LE↓	3*		3*		ns

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54AS373			SN74AS373			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_I = −18 mA			−1.2			−1.2	V
V_{OH}	V_{CC} = 4.5 V to 5.5 V,	I_{OH} = −2 mA	V_{CC}−2			V_{CC}−2			V
	V_{CC} = 4.5 V	I_{OH} = −12 mA	2.4	3.2					
		I_{OH} = −15 mA				2.4	3.3		
V_{OL}	V_{CC} = 4.5 V	I_{OL} = 32 mA		0.27	0.5				V
		I_{OL} = 48 mA					0.32	0.5	
I_{OZH}	V_{CC} = 5.5 V,	V_O = 2.7 V			50			50	µA
I_{OZL}	V_{CC} = 5.5 V,	V_O = 0.4 V			−50			−50	µA
I_I	V_{CC} = 5.5 V,	V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = 5.5 V,	V_I = 2.7 V			20			20	µA
I_{IL}	V_{CC} = 5.5 V,	V_I = 0.4 V		−0.02	−0.5		−0.02	−0.5	mA
I_O‡	V_{CC} = 5.5 V,	V_O = 2.25 V	−30		−112	−30		−112	mA
I_{CC}	V_{CC} = 5.5 V	Outputs high		55	90		55	90	mA
		Outputs low		55	85		55	85	
		Outputs disabled		65	100		65	100	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

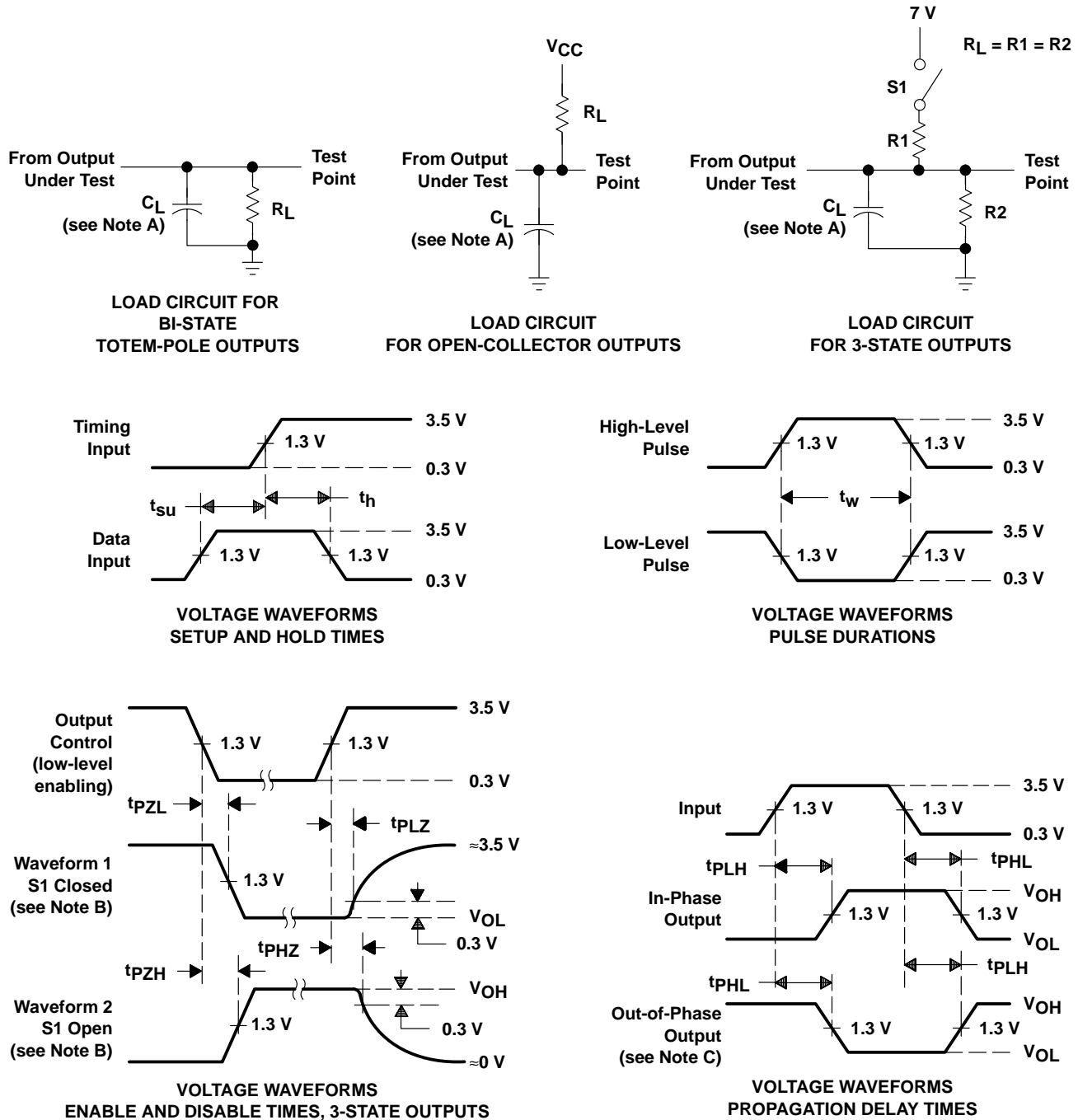| PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX§				UNIT
			SN54AS373		SN74AS373		
			MIN	MAX	MIN	MAX	
t_{PLH}	D	Q	3	9	3.5	6	ns
t_{PHL}			3	8	3.5	6	
t_{PLH}	LE	Any Q	6.5	14.5	6.5	11.5	ns
t_{PHL}			5	9	5	7.5	
t_{PZH}	$\overline{OE}$	Any Q	2	7.5	2	6.5	ns
t_{PZL}			4.5	10.5	4.5	9.5	
t_{PHZ}	$\overline{OE}$	Any Q	3	10	3	6.5	ns
t_{PLZ}			3	8	3	7	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

TEXAS
INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES

LOAD CIRCUIT FOR BI-STATE TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR OPEN-COLLECTOR OUTPUTS

LOAD CIRCUIT FOR 3-STATE OUTPUTS

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS PULSE DURATIONS

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR $\leq$ 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
83020012A	ACTIVE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125	83020012A SNJ54ALS 373AFK	Samples
8302001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001RA SNJ54ALS373AJ	Samples
8302001SA	ACTIVE	CFP	W	20		TBD	Call TI	Call TI	-55 to 125	8302001SA SNJ54ALS373AW	Samples
JM38510/37203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37203B2A	Samples
JM38510/37203BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37203BRA	Samples
M38510/37203B2A	ACTIVE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125	JM38510/ 37203B2A	Samples
M38510/37203BRA	ACTIVE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125	JM38510/ 37203BRA	Samples
SN54ALS373AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS373AJ	Samples
SN54AS373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS373J	Samples
SN74ALS373ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS373ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G373A	Samples
SN74ALS373ADBRG4	ACTIVE	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70	G373A	Samples
SN74ALS373ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ADWE4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	ALS373A	Samples
SN74ALS373ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ADWRE4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	ALS373A	Samples
SN74ALS373ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS373AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS373AN	Samples
SN74ALS373AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS373ANE4	ACTIVE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70	SN74ALS373AN	Samples
SN74ALS373ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ANSRE4	ACTIVE	SO	NS	20		TBD	Call TI	Call TI	0 to 70	ALS373A	Samples
SN74ALS373ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74AS373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS373	Samples
SN74AS373DWE4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	AS373	Samples
SN74AS373DWG4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	AS373	Samples
SN74AS373DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	AS373	
SN74AS373DWRE4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS373DWRG4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS373N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS373N	Samples
SN74AS373N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74AS373NE4	ACTIVE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70	SN74AS373N	Samples
SN74AS373NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS373	Samples
SN74AS373NSRE4	ACTIVE	SO	NS	20		TBD	Call TI	Call TI	0 to 70	74AS373	Samples
SN74AS373NSRG4	ACTIVE	SO	NS	20		TBD	Call TI	Call TI	0 to 70	74AS373	Samples
SNJ54ALS373AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	83020012A SNJ54ALS 373AFK	Samples
SNJ54ALS373AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001RA SNJ54ALS373AJ	Samples
SNJ54ALS373AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001SA SNJ54ALS373AW	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AS373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 373FK	Samples
SNJ54AS373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS373J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS373A, SN54AS373, SN74ALS373A, SN74AS373 :

● Catalog: SN74ALS373A, SN74AS373

● Military: SN54ALS373A, SN54AS373

NOTE: Qualified Version Definitions:

- ● Catalog - TI's standard catalog product

- ● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS373ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS373ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS373ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AS373NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS
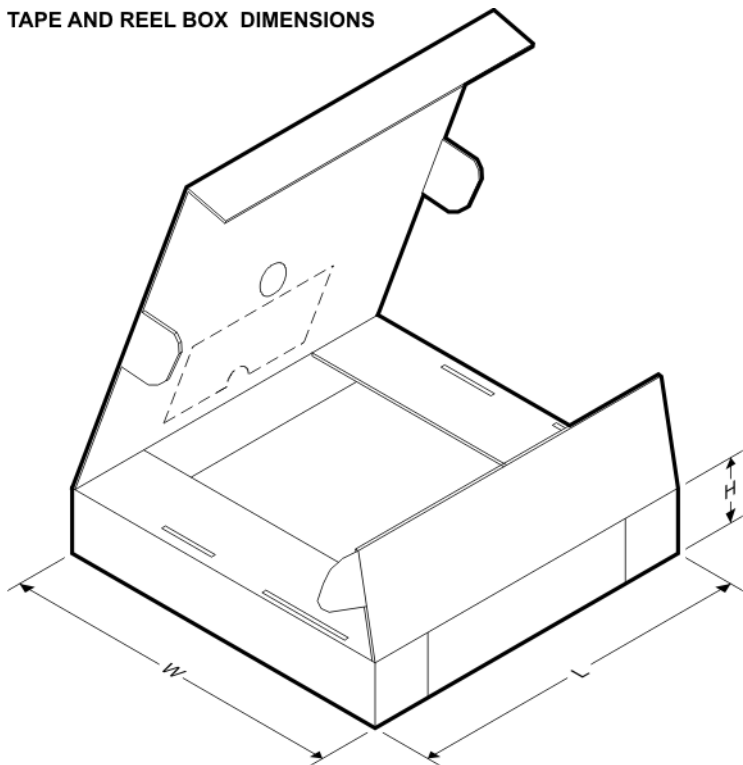
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS373ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS373ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS373ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS373NSR	SO	NS	20	2000	367.0	367.0	45.0

DIM PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

C

0.065 (1,65)
0.045 (1,14)

1   7

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

A

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

0°—15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package is hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E.   Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

W (R−GDFP−F20)   CERAMIC DUAL FLATPACK

Base and Seating Plane

$\dfrac{0.045\ (1,14)}{0.026\ (0,66)}$

$\dfrac{0.300\ (7,62)}{0.245\ (6,22)}$

$\dfrac{0.100\ (2,45)}{0.045\ (1,14)}$

$\dfrac{0.009\ (0,23)}{0.004\ (0,10)}$

0.320 (8,13) MAX

1   20

$\dfrac{0.022\ (0,56)}{0.015\ (0,38)}$

0.540 (13,72) MAX

0.050 (1,27)

0.005 (0,13) MIN
4 Places

10   11

$\dfrac{0.370\ (9,40)}{0.250\ (6,35)}$

$\dfrac{0.370\ (9,40)}{0.250\ (6,35)}$

4040180−4/F   04/14

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within Mil−Std 1835 GDFP2−F20

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

4040140/D 01/11

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
          C. This package can be hermetically sealed with a metal lid.
          D. Falls within JEDEC MS−004

N (R−PDIP−T**)   PLASTIC DUAL−IN−LINE PACKAGE
16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
△C MS−001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) △D

0.045 (1,14) / 0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
△C Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
△D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

0.512 (13,00)
0.496 (12,60)

20   11

0.419 (10,63)
0.393 (9,97)

0.299 (7,60)
0.291 (7,40)

1   10

Pin 1
Index Area

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.050 (1,27)

0.104 (2,65) Max

0.012 (0,30)
0.004 (0,10)

0.013 (0,33)
0.008 (0,20)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)

0°−8°

0.050 (1,27)
0.016 (0,40)

4040000−4/G 01/11
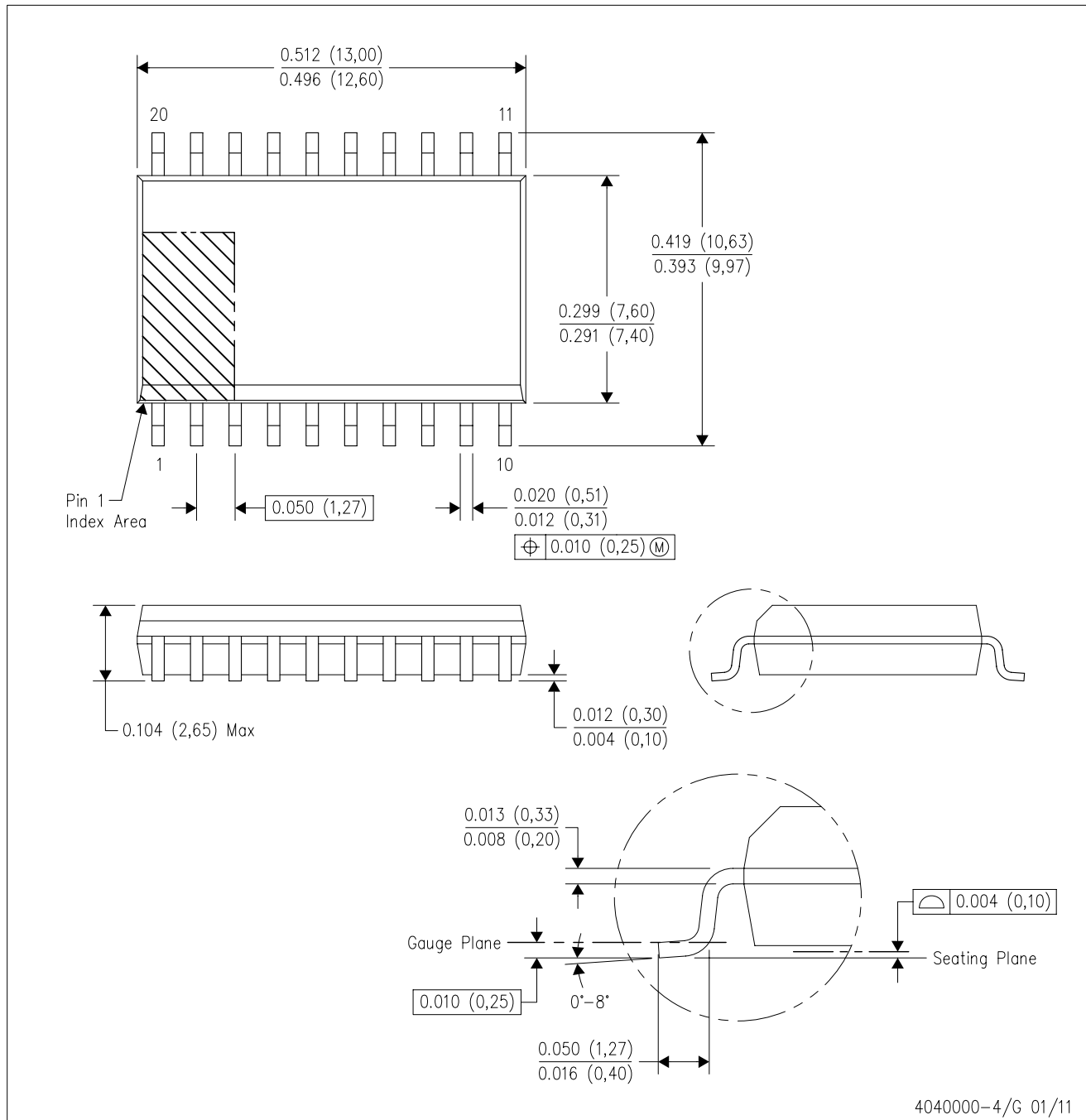
NOTES: A.   All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D.   Falls within JEDEC MS−013 variation AC.

DW (R−PDSO−G20)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

20x0,6 →| |←   →| |←18x1,27

9,4

→| |←—20x0,55   →| |←18x1,27

20x1,95

9,4

Non Solder Mask Define Pad

|← 0,6 →|

2,0

0,07
All Around

Solder Mask Opening
(Note E)

Pad Geometry
(Note C)
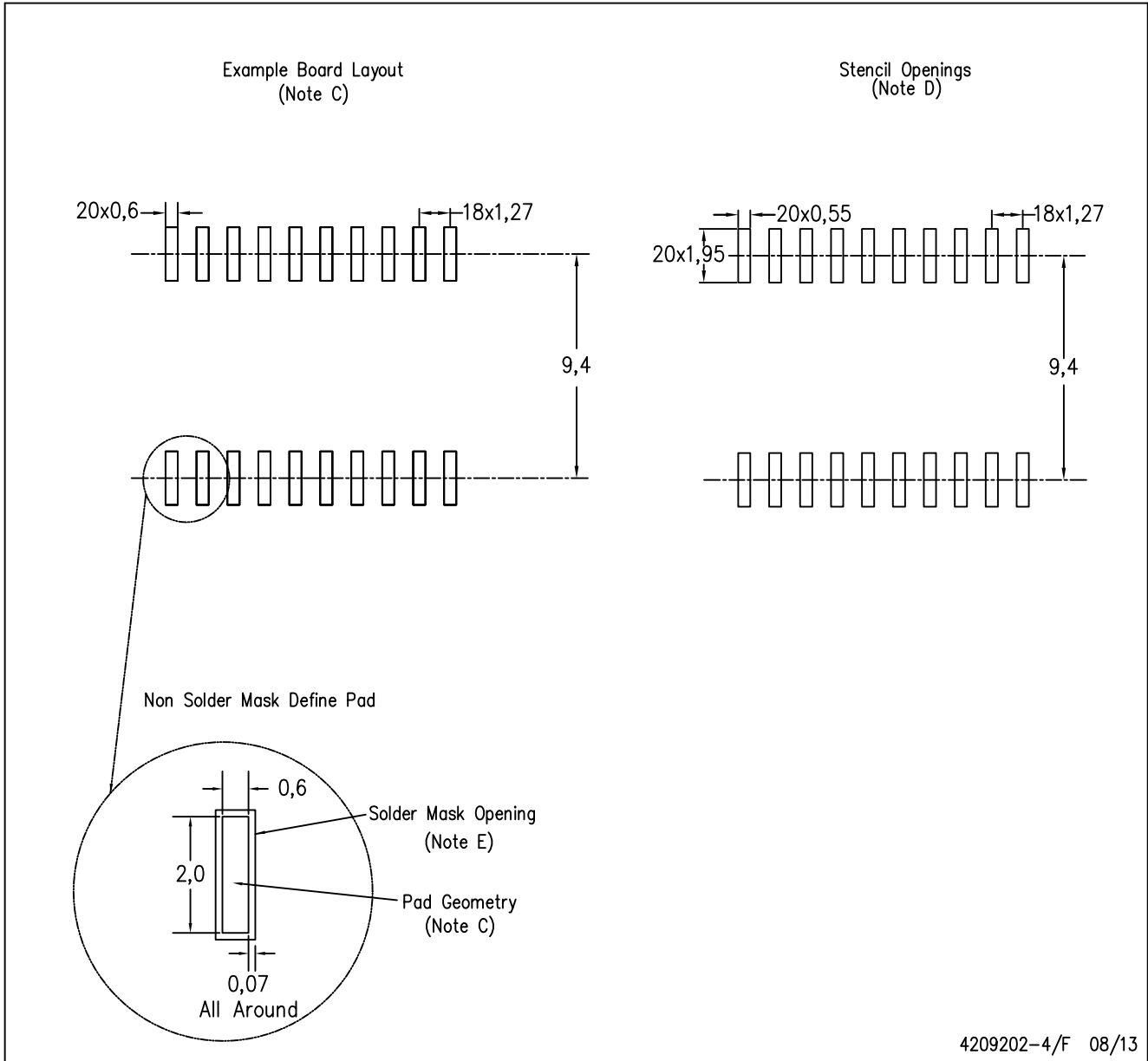
4209202−4/F   08/13

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Refer to IPC7351 for alternate board design.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

**TEXAS
INSTRUMENTS**
www.ti.com

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

PINS ** / DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

1,27

0,51 / 0,35   ⊕ 0,25 Ⓜ

14   8

5,60 / 5,00   8,20 / 7,40

1   7

A

0,15 NOM

Gage Plane

0,25

0°–10°

1,05 / 0,55

0,15 / 0,05

2,00 MAX

Seating Plane

△ 0,10

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		